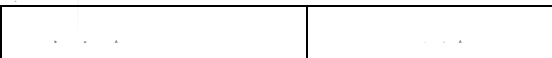
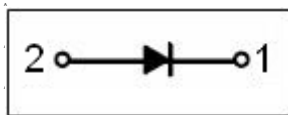




.....



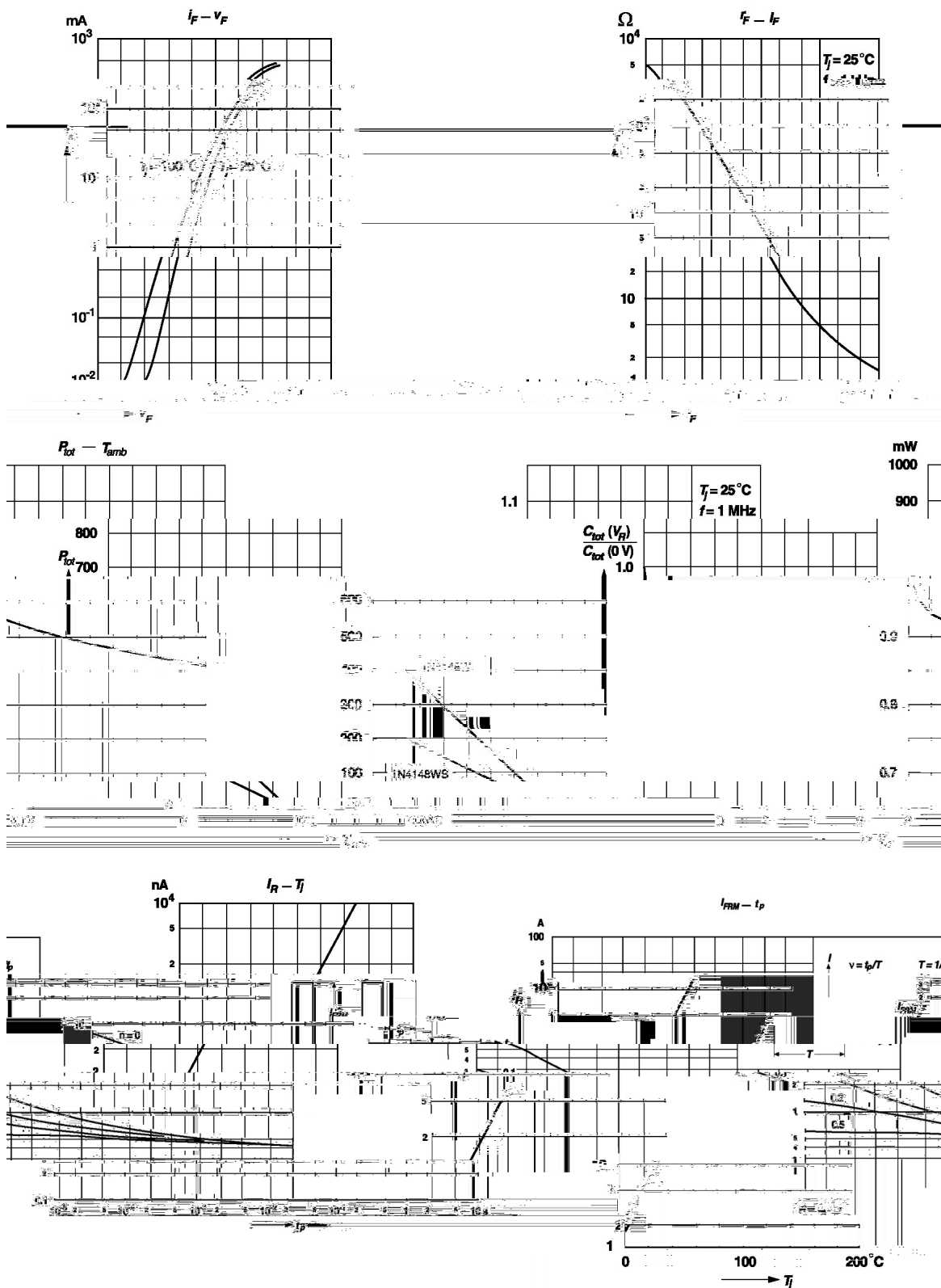
.....

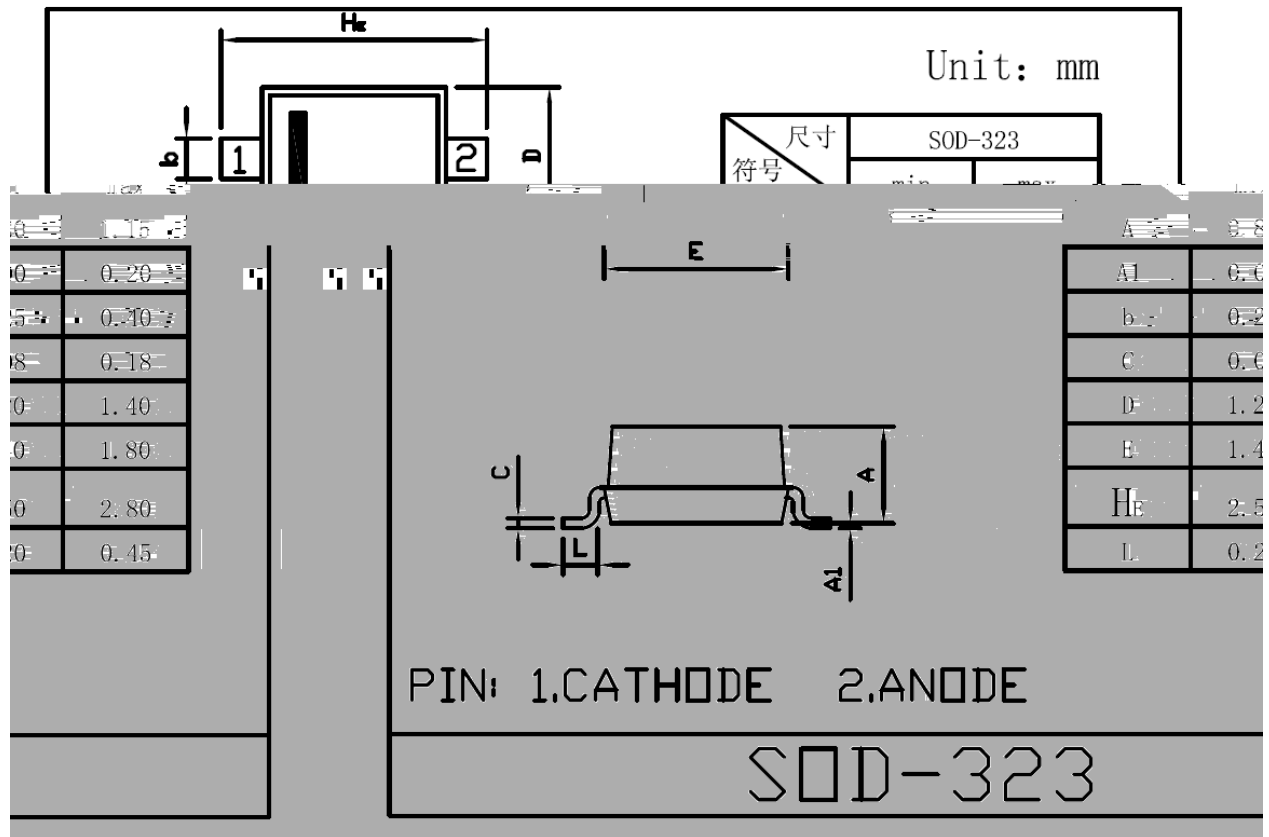


3

3

[illegible]







.....

..



..

..

..

..

..

..

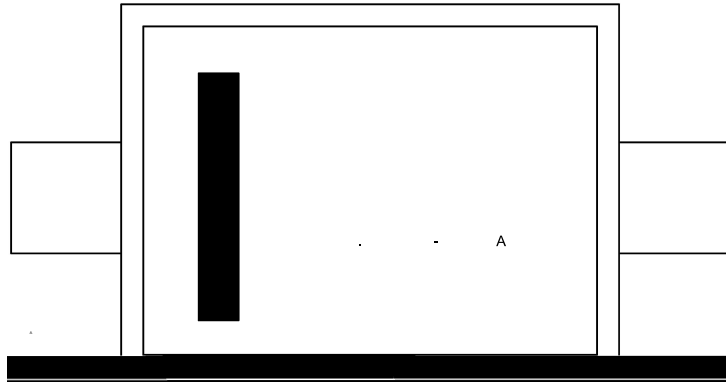
..

..

..

..

..



..

..

..

..

..

..

..

..

..

..

..

..

..

..

..

..

..

..

..

..

..

..

..

..

..

Q
A2

.....

.....

.....

..

..

.....



Temperature Profile for IR Reflow Soldering(Pb-Free)

说明：
、预热温度 ~ °C，时间 ~ °C
、峰值温度 ± °C，时间持续为 ± °C
、焊接制程冷却速度为 ~ °C

温度： ± °C 时间： ± °C

卷盘包装

Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box	Outer Box
--------------------	-------------------------	------------------------	------------------------------	------------------------	------	-----------	-----------